

Description

Features	Application
<ul style="list-style-type: none"> ● 500V, 9A ● $R_{DS(ON)} = 0.67\Omega$ (Typ.) @ $V_{GS} = 10V$, $I_D = 4.5A$ ● Fast Switching ● 100% Avalanche Tested ● Improved dv/dt Capability 	<ul style="list-style-type: none"> ● Switch Mode Power Supply (SMPS) ● Uninterruptible Power Supply (UPS) ● Power Factor Correction (PFC)

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.					Units
		TO-220C	TO-263	TO-220F	TO-252	TO-251	
V_{DSS}	Drain-Source Voltage			500			V
V_{GSS}	Gate-Source Voltage			± 30			V
I_D	Continuous Drain Current	$T_C = 25^\circ C$		9			A
		$T_C = 100^\circ C$		5.4			A
I_{DM}	Pulsed Drain Current ^{note1}			36			A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}			198			mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	150	150	63	100	100
R_{eJC}	Thermal Resistance, Junction to Case	0.83	0.83	1.98	1.25	1.25	°C/W
R_{eJA}	Thermal Resistance, Junction to Ambient	62.5	62.5	62.5	100	100	°C/W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150					°C

Electrical Characteristics (T_C=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	500	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V, T _J = 25°C	-	-	1	μA
I _{GSS}	Gate to Body Leakage Current	V _{GS} = 0V, V _{GS} = ±30V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.0	-	4.0	V
R _{D(on)}	Static Drain-Source On-Resistance <small>note3</small>	V _{GS} = 10V, I _D = 4.5A	-	0.67	0.84	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	-	891	-	pF
C _{oss}	Output Capacitance		-	110	-	pF
C _{rss}	Reverse Transfer Capacitance		-	14	-	pF
Q _g	Total Gate Charge	V _{DD} = 400V, I _D = 9A, V _{GS} = 10V	-	22	-	nC
Q _{gs}	Gate-Source Charge		-	4.3	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	13	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} = 250V, I _D = 9A, R _G = 25Ω	-	15	-	ns
t _r	Turn-On Rise Time		-	18	-	ns
t _{d(off)}	Turn-Off Delay Time		-	80	-	ns
t _f	Turn-Off Fall Time		-	35	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	9	-	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	36	-	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} = 9A, T _J = 25°C	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 9A, di/dt = 100A/μs	-	300	-	ns
Q _{rr}	Reverse Recovery Charge		-	4.1	-	μC

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. I_{AS} = 4.5A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C

3. Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%

Typical Performance Characteristics

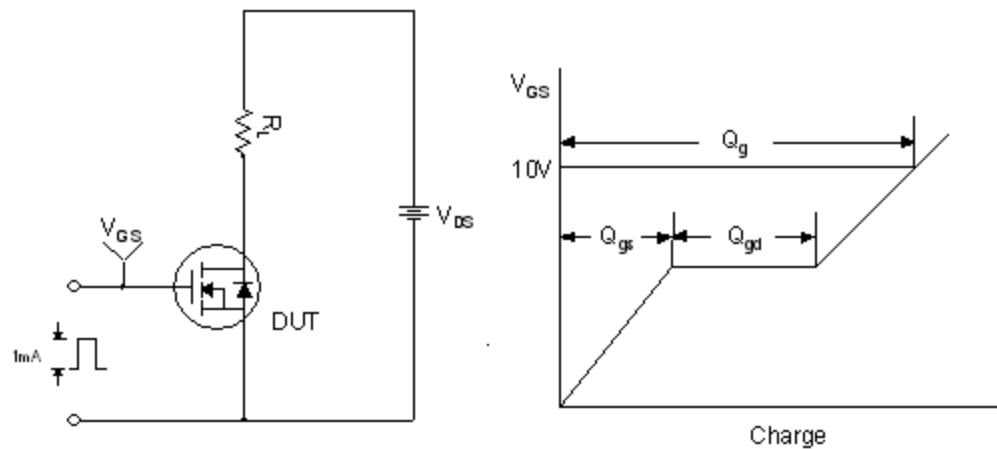


Figure 1. Gate Charge Test Circuit & Waveform

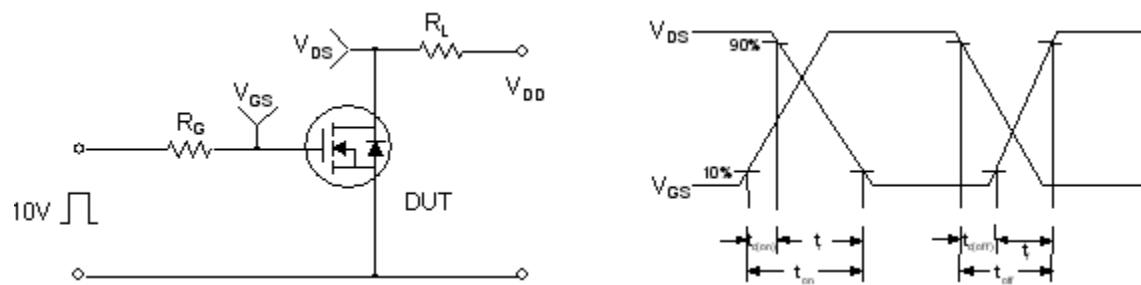


Figure 2. Resistive Switching Test Circuit & Waveforms

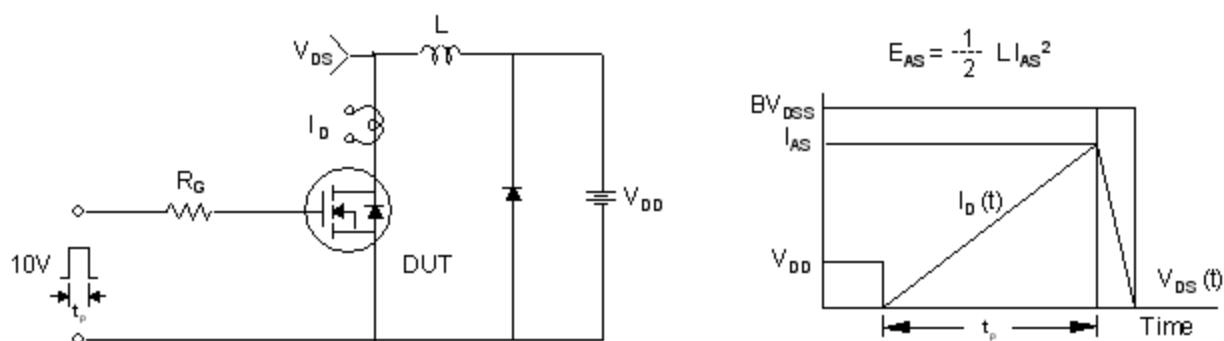
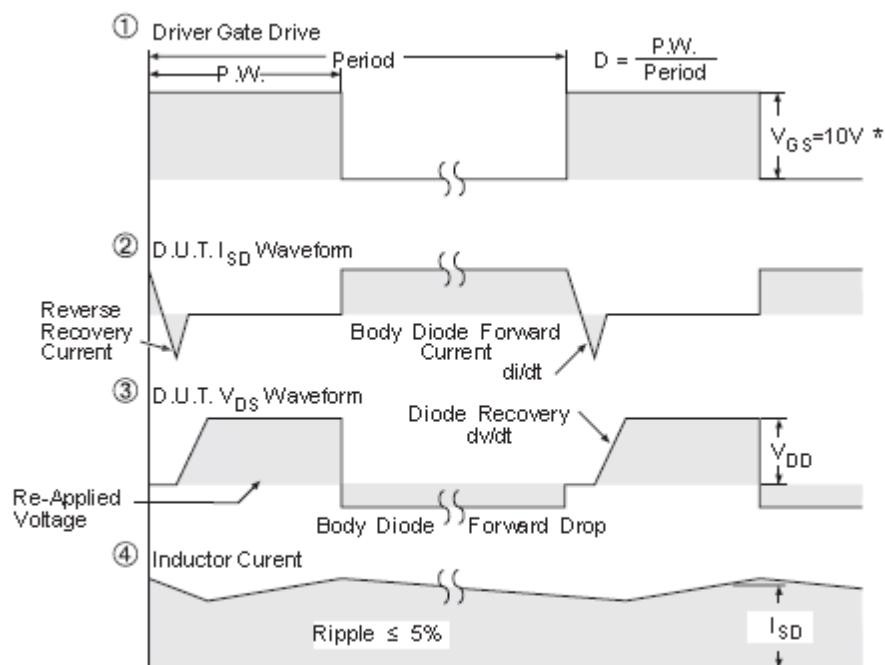
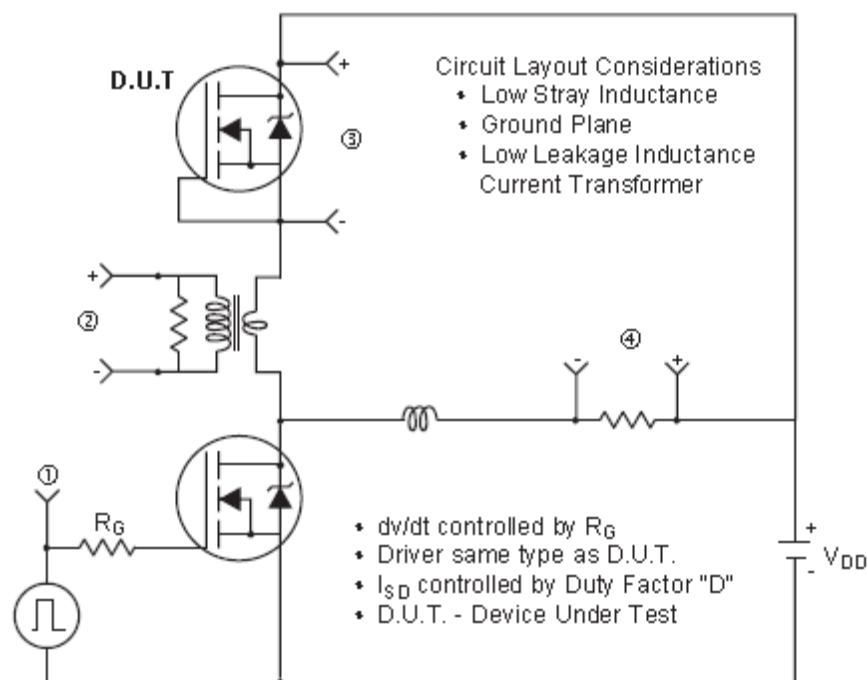


Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms



* $V_{GS} = 5V$ for Logic Level Devices

Figure 4. Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)